

Exhibit D



RECEIVE



TJD



Micron Technology, Inc.
8000 S. Federal Blvd.
PO Box 100
Dallas, TX 75224
214-343-7000

Tom D'Amico
Dickstein, Sharp, Morin,
& Oshinsky
2101 L Street N.W.
Washington, DC 20037

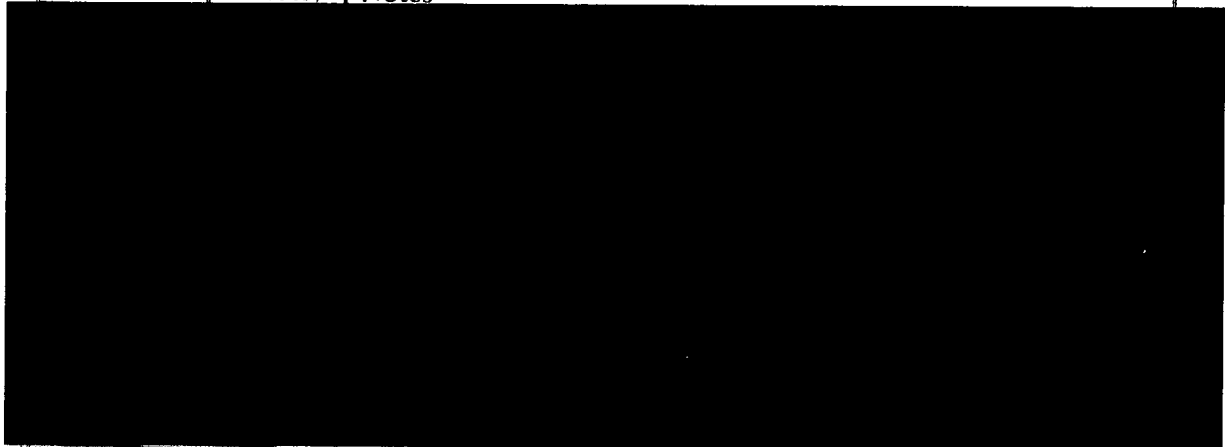
M4005.1005/P1005

Re: New Disclosures

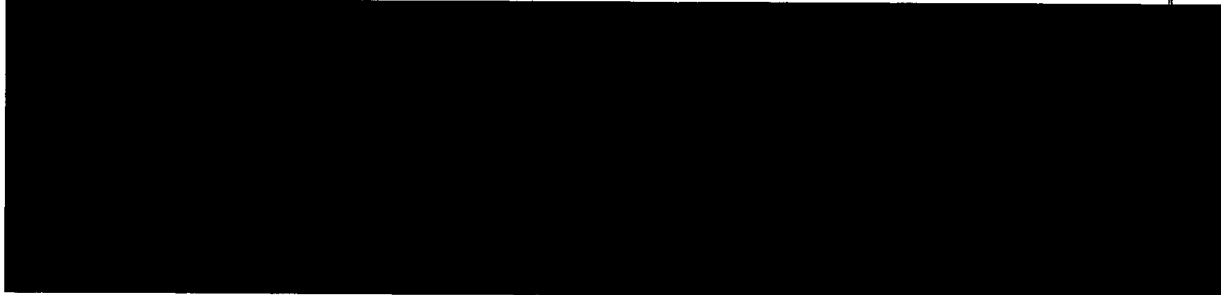
Dear Tom:

The following disclosures have been assigned to your docket:

Docket #	Priority	Notes
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03-0953	Regular	
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Page 2

Please prepare and file a patent application with the U.S. Patent and Trademark Office on behalf of Micron Technology, Inc. for each. Where possible, please draft system, product and process claims for each. If you have any questions regarding these disclosures or any other disclosures, please feel free to call.

Sincerely,

A handwritten signature in cursive script that reads "Stacy Summers".

Stacy Summers
Patent Assistant

Phone: 208/368-4591

Fax: 208/368-5606

Exhibit E

DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP

2101 L Street NW • Washington, DC 20037-1526

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E-Mail Address: DAmicoT@dsmo.com

November 18, 2003

VIA UPS

Ms. Stacy L. Summers
Micron Technology, Inc.
8000 S. Federal Way
Boise, Idaho 83707-0006

**PRIVILEGED AND CONFIDENTIAL:
ATTORNEY-CLIENT COMMUNICATION**

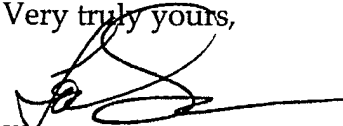
Re: Proposed U.S. Patent Application
Title: A DIE PACKAGE HAVING AN ADHESIVE FLOW RESTRICTION
AREA
Inventors: Bret K. Street, et al.
Micron Reference: 03-0953
Our Reference: M4065.1005/P1005

Dear Stacy:

Enclosed are five (5) copies of a draft patent application for the above-referenced invention.

Please have the inventors review the application to ensure that it accurately and completely describes the invention. We look forward to receiving comments so that the application can be filed with the U.S. Patent and Trademark Office as soon as possible. If any changes, corrections or additions are needed, please let us have the details. Please direct your comments to Dipu A. Doshi at (202) 572-2604.

Very truly yours,



Thomas J. D'Amico

TJD/DAD/cdl
Enclosures